

SOT1025-1

plastic thermal enhanced ultra thin quad flat package; no leads; 60 terminals; UTLP based

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HUQFN60U
Package type industry code	HUQFN60U
Package style descriptive code	HUQFN (thermal enhanced ultra thin quad flatpack; no leads)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	[tbd]	-	[tbd]	0.6	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	60	-	

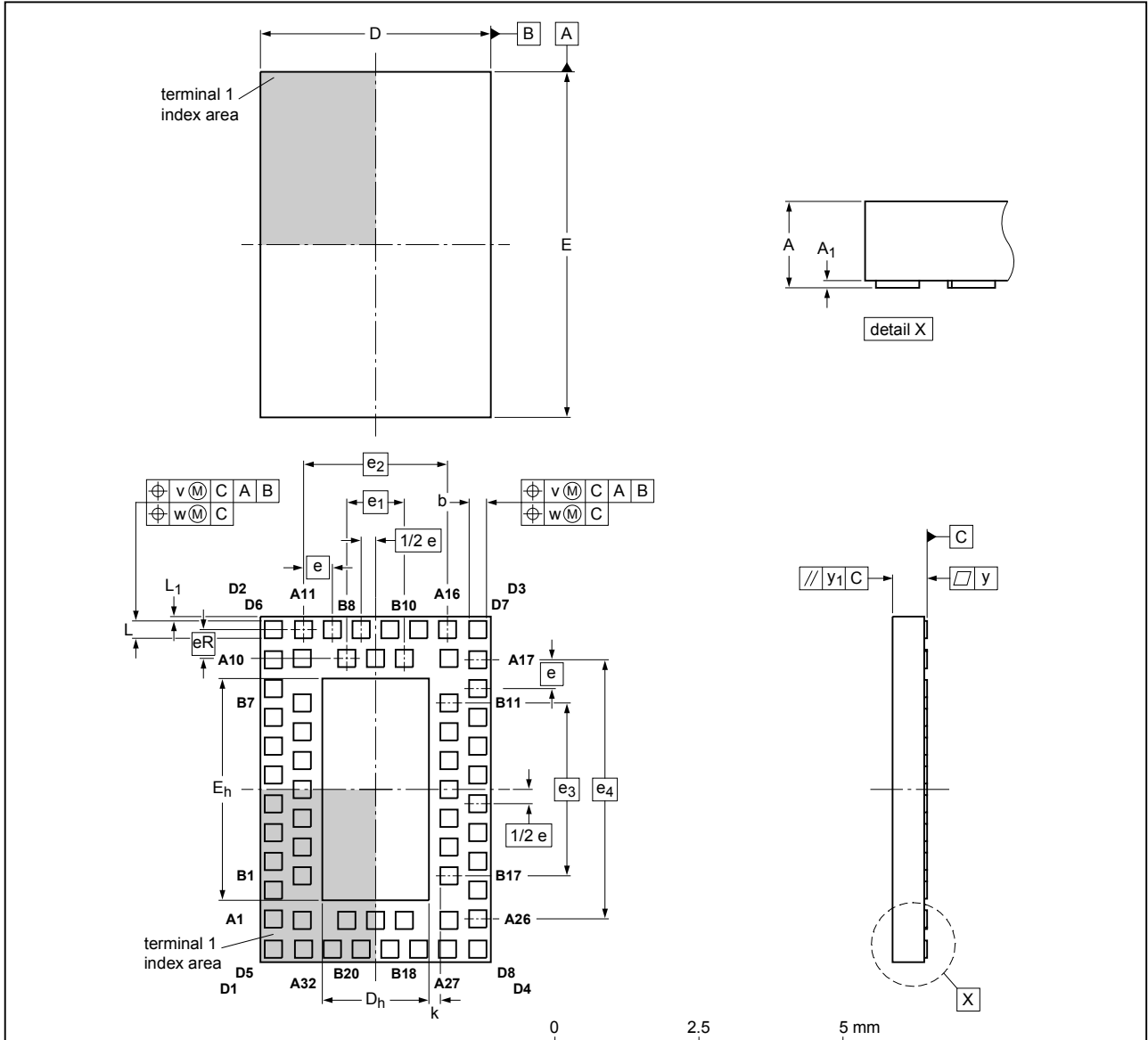


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2. Package outline

HUQFN60U: plastic thermal enhanced ultra thin quad flat package; no leads
60 terminals; UTLP based; body 4 x 6 x 0.55 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max	A ₁	b	D	D _h	E	E _h	e	e ₁	e ₂	e ₃	e ₄	eR	k	L	L ₁	v	w	y	y ₁
mm	0.6	0.05 0.00	0.35 0.25	4.1 3.9	1.9 1.8	6.1 5.9	3.9 3.8	0.5	1	2.5	3	4.5	0.5	0.25 0.15	0.35 0.25	0.125 0.025	0.07	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1025-1	---	---	---			07-08-28 07-11-14

Fig. 1. Package outline HUQFN60U (SOT1025-1)

3. Legal information

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